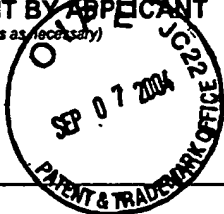


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First Named Inventor Farrar, Paul

Group Art Unit 1763

Examiner Name Unknown

Sheet 1 of 1

Attorney Docket No: 1303.096US1

US PATENT DOCUMENTS

Examiner Initial *	USP Document Number	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	Filing Date if Appropriate
82	US2001/0014524	08/16/2001	Farrar, Paul A.	438	613	02/19/1999
	US2002/0034581	03/21/2002	Farrar, Paul A., et al.	427	58	02/20/2001
	US-3,959,047	05/25/1976	Alberts, G. S., et al.	156	8	09/30/1974
	US-5,457,345	10/10/1995	Cook, H. C., et al.	257	766	01/14/1994
	US-5,461,257	10/24/1995	Hundt, M. J.	257	707	03/31/1994
	US-5,642,261	06/24/1997	Bond, R. H., et al.	361	704	06/30/1994
	US-5,693,572	12/02/1997	Bond, R. H., et al.	437	209	01/18/1996
	US-6,136,689	10/24/2000	Farrar, Paul A.	438	626	08/14/1998
80	US-6,435,396	08/20/2002	Eldridge, Jerome M.	228	33	04/10/2000

FOREIGN PATENT DOCUMENTS

Examiner Initials*	Foreign Document No	Publication Date	Name of Patentee or Applicant of cited Document	Class	Subclass	T ²
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OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS

Examiner Initials*	Cite No	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.	T ²
80		ANONYMOUS, "Combination Process for Final Metal Lines and Metal Terminals", Kenneth Mason Publications Ltd, Research Disclosure No. 342, England, (Oct. 1992), 1 page	
		ANONYMOUS, "Process for High Density of Chip Terminals on Large Wafers", Kenneth Mason Publications Ltd, Research Disclosure No. 02, England, (Feb. 1993), 1 page	
		BABIARZ, A J., "Key Process Controls for Underfiling Flip Chips", <u>Solid State Technology</u> , 40(4), (April 1997), 77-8, 81, 83	
		JONES, P, et al., "Bumped Wafers, Worth Their Weight in Gold?", <u>Advanced Packaging</u> , 8(1), (January 1997), 54-57	
		MARCOTTE, V. C., "Review of Flip Chip Bonding", <u>Proceedings of the 2nd ASM International Electronic Materials and Processing Congress</u> , 24-28 April 1989, Philadelphia, PA, (1989), 73-81	
		MINGES, MERRILL, "Electronic Materials Handbook", <u>Materials Park, OH: ASM International</u> , (1989), 301, 440	
		PUTTLITZ, KARL J., et al., "Solder Transfer Technique for Flip-Chip and Electronic Assembly Applications", <u>IEEE Transactions on Components, Packaging and Manufacturing Technology</u> , Part C, Volume 21, No. 3, (July 1998), 182-188	
80		RYAN, J. G., "Technology Challenges for Advanced Interconnects", <u>Advances in Metallization and Interconnect Systems for ULSI Applications</u> , September 30 - October 2, 1997, San Diego CA, (1997), 1-5	

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